

/ Revised record

版本	修订日期	有修订的页码	修订涉及的内容	拟制	审核
D	2017-5				
E	2021-1-27	4/7	更新外形图 e0.5-0.7 改为 0.5-0.8 ,包装资料 5 盒改为 7 盒	黄超	刘晓荣

/ Descriptions

1.0A 表面贴装肖特基桥，薄型 MBF 封装。
1.0A Surface Mount Schottky Bridge, MBF thin package。

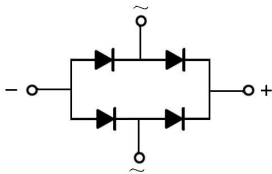
/ Features

浪涌电流大，反向电压：40V~200V，正向电流：1.0A，适用于表面贴装。无卤产品。
High Surge Current Capability,Reverse Voltage:40to200V,Forward Current: 1.0 A,Designed for Surface Mount Application.Halogen free product.

/ Applications

一般用途。
General purpose.

/ Equivalent Circuit



/ Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

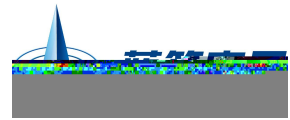


/ Marking

见印章说明。See Marking Instructions.

MB14F~MB120F

Rev.E Jan. 2021



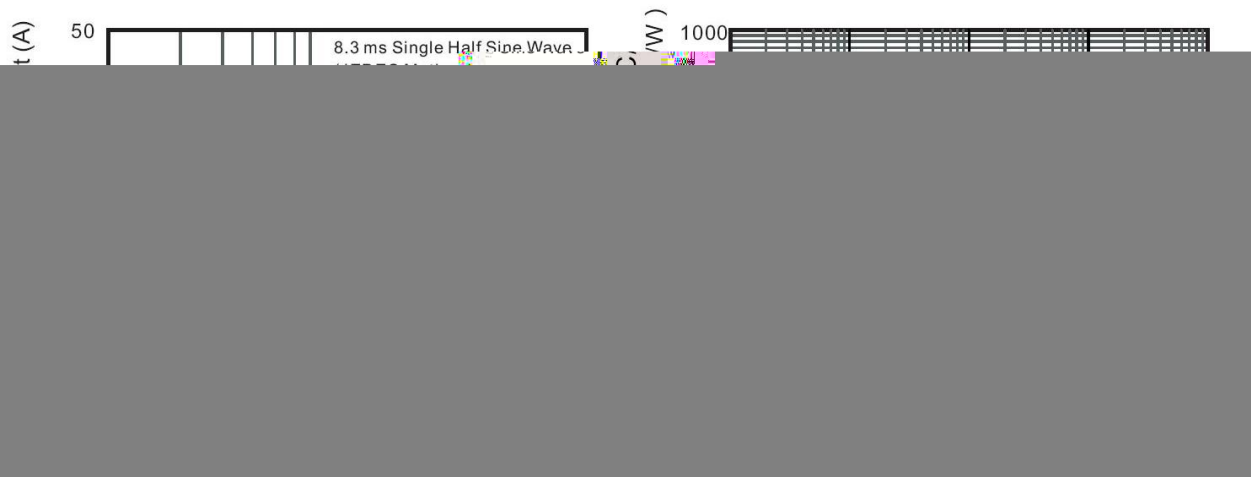
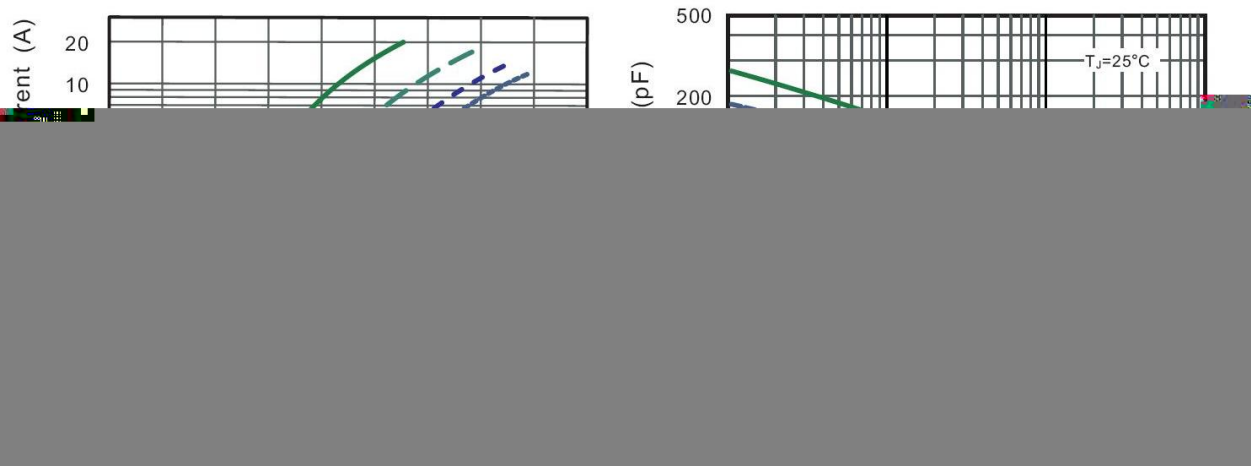
DATA SHEET

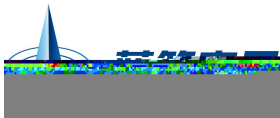
参数
Parameter

符号
Symbol

MB14F MB16F MB18F MB110F MB115F MB120F

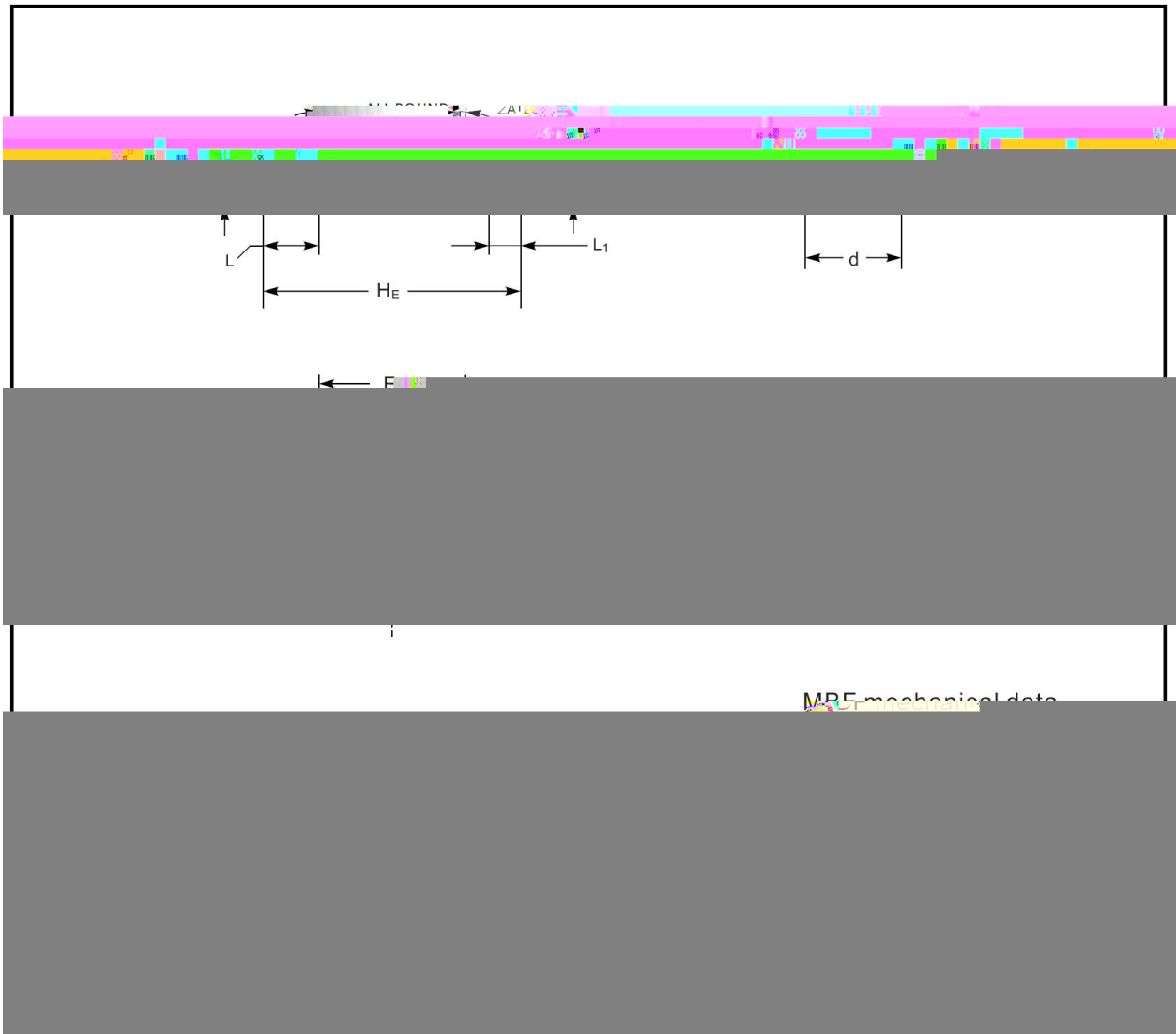
/ Electrical Characteristic Curve

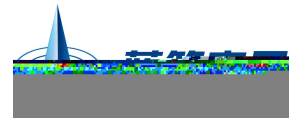




/ Package Dimensions

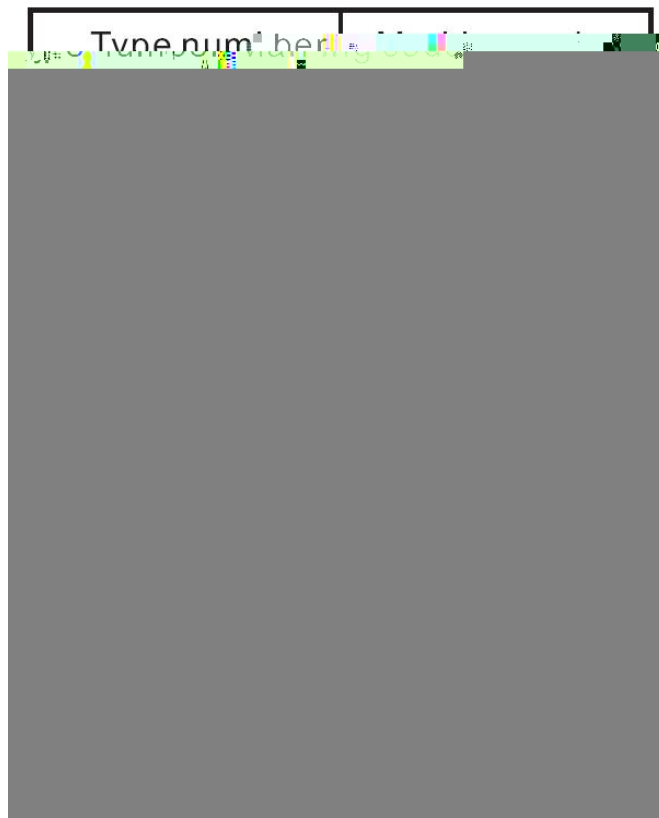
MBF



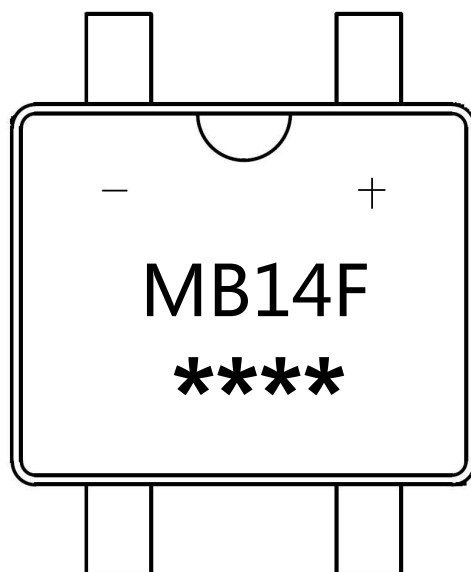


/ Marking Instructions

Marking



/ Marking Instructions



说明

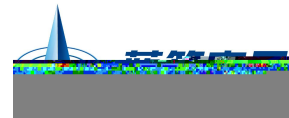
MB14F : 为型号代码

**** : 为生产批号追溯码，第 1 个*为年月代码，后面 3 个*为当月小批号代码

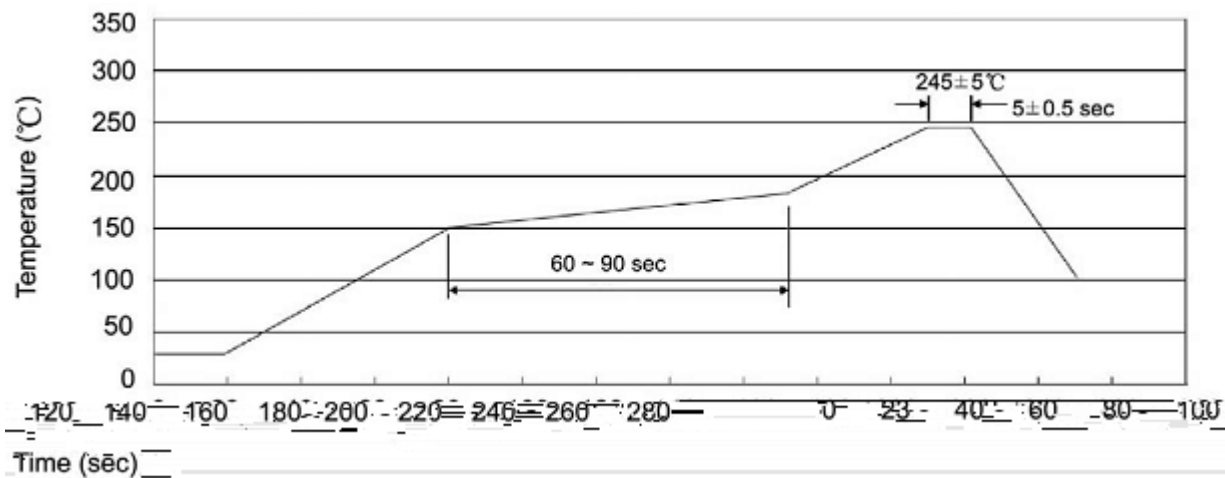
Note:

MB14F : Product Type Code

**** : Lot No. Code , The 1st * means:YM Code , The last 3 * means:little Lot No Code



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

/ Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

/ Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
MBF	5000	2	10000	7	70000	13" ×12	336X336X40	380X335X366